L	Hits	Search Text	DB	Time stamp
Number	ļ			L
1	1	("5925898").PN.	USPAT	2003/09/25 10:12
2	12569	(chip or die or led or (light near	USPAT;	2003/09/25
1		(emiiter or receiver))) and ((frame or	US-PGPUB;	12:30
1	)	ring) with (substrate))	EPO; JPO;	1
l			DERWENT;	1
1	1		IBM_TDB	
3	1804	((chip or die or led or (light near	USPAT;	2003/09/25
	J	(emiiter or receiver))) and ((frame or	US-PGPUB;	12:32
	1	ring) with (substrate))) and (((frame or	EPO; JPO;	1
		ring) and substrate) with (solder or	DERWENT;	
] _	1200	pad))	IBM_TDB	1 ( (
4	1309	(((chip or die or led or (light near	USPAT;	2003/09/25
	1	(emiiter or receiver))) and ((frame or	US-PGPUB;	12:31
}	<b>{</b>	ring) with (substrate))) and (((frame or	EPO; JPO;	1
		ring) and substrate) with (solder or pad))) and (@ad<20010224)	DERWENT; IBM TDB	1
5	1	("4636647").PN.	USPAT	2003/09/25
~		( .00001/ / . EN .	JULIA	12:18
6	695	(frame or ring) and ((transparent or	USPAT;	2003/09/25
,		light) with substrate) and (solder with	US-PGPUB;	12:26
		(adhesive or paste or bond))	EPO; JPO;	12.20
	}		DERWENT;	j
			IBM TDB	İ
7	552	((frame or ring) and ((transparent or	USPAT;	2003/09/25
		light) with substrate) and (solder with	US-PGPUB;	12:31
		(adhesive or paste or bond))) and (chip	EPO; JPO;	
		or die or led or (light near (emiiter or	DERWENT;	\
		receiver)))	IBM_TDB	
8	378	(((frame or ring) and ((transparent or	USPAT;	2003/09/25
		light) with substrate) and (solder with	US-PGPUB;	12:32
		(adhesive or paste or bond))) and (chip	EPO; JPO;	1
		or die or led or (light near (emiiter or	DERWENT;	1
9	624	receiver)))	IBM_TDB   USPAT;	2003/09/25
	024	light) with substrate) and (solder with	US-PGPUB;	12:32
		(adhesive or paste or bond))) and (chip	EPO; JPO;	12.32
l		or die or optical or led or (light near	DERWENT;	[
		(emitter or receiver)))	IBM TDB	}
10	431	(((frame or ring) and ((transparent or	USPAT;	2003/09/25
1		light) with substrate) and (solder with	US-PGPUB;	12:32
ŀ		(adhesive or paste or bond))) and (chip	EPO; JPO;	
		or die or optical or led or (light near	DERWENT;	
ļ		(emitter or receiver)))) and	IBM_TDB	1
		(@ad<20010224)		
11	132		USPAT;	2003/09/25
į		light) with substrate) and (solder with	US-PGPUB;	12:35
		(adhesive or paste or bond))) and (chip	EPO; JPO;	
Į.	ļ	or die or optical or led or (light near	DERWENT;	}
ļ		<pre>(emitter or receiver))) ) and (@ad&lt;20010224)) and ((frame or ring) with</pre>	IBM_TDB	
ĺ	i	(solder or pad or tab or bump))		1
		(Solder or bad of can of nump))	L	L